

# P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
- 30	0.173 at V <sub>GS</sub> = - 10 V	- 0.98 <sup>a</sup>	3.25		
	0.243 at V <sub>GS</sub> = - 4.5 V	- 0.83	3.25		

### **FEATURES**

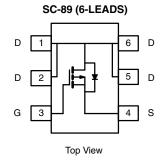
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

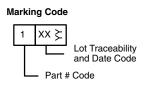


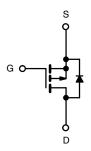
ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

· Load Switch







Ordering Information: Si1073X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 30	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Dunis Comment /T 450 °C\d	T <sub>A</sub> = 25 °C	L-	- 0.98 <sup>b, c</sup>		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C	l D	- 0.78 <sup>b, c</sup>	Α Α	
Pulsed Drain Current		I <sub>DM</sub>	- 8	^	
Avalanche Current	L = 0.1 mH		- 6		
Repetitive Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	1.8	mJ	
ontinuous Source-Drain Diode Current T <sub>A</sub> = 25 °C		I <sub>S</sub>	0.2 <sup>b, c</sup>	A	
Mariana Barra Birainatian	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.236 <sup>b, c</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	] '	0.151 <sup>b, c</sup>		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Marian and Langeline to Americanth d	t ≤ 5 s	R <sub>thJA</sub>	440	530	°C/W	
Maximum Junction-to-Ambient <sup>b, d</sup>	Steady State		540	650	C/VV	

#### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 650 °C/W.

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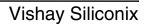
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, I}_{D} = -250 \mu\text{A}$	- 30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		- 30.7			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		3.78		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1		
		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C			- 10	- μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = -10 \text{ V}$	- 8			Α	
D. 1.0	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 0.98 A		0.144	0.173	Ω	
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS} = -4.5 \text{ V}, I_D = -0.83 \text{ A}$		0.202	0.243		
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 0.98 A		3.52		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			265		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		51			
Reverse Transfer Capacitance	C <sub>rss</sub>			39			
Total Gate Charge	Q <sub>g</sub> Q <sub>gs</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.98 \text{ A}$		3.25	4.88		
				6.3	9.45		
Gate-Source Charge		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -0.98 \text{ A}$		1.02			
Gate-Drain Charge	$Q_{gd}$			1.47			
Gate Resistance	$R_{g}$	f = 1 MHz		14	21	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			6	9		
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_L = 19.2 \Omega$		10	15		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -0.78 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		14	21		
Fall Time	t <sub>f</sub>			6	9	ne	
Turn-On Delay Time	n-On Delay Time t <sub>d(on)</sub>			26	39	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_L = 22.72 \Omega$		28	42		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 0.66 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		28	42		
Fall Time	t <sub>f</sub>			12	18		
<b>Drain-Source Body Diode Characteristi</b>	cs						
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	_			8	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 0.63 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			14.3	21.45	nC	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L 0.7 A dl/dt = 100 A/vs		12.16	18.25	ns	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -0.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		11.1			
Reverse Recovery Rise Time	t <sub>b</sub>	t <sub>b</sub>		3.2			

#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

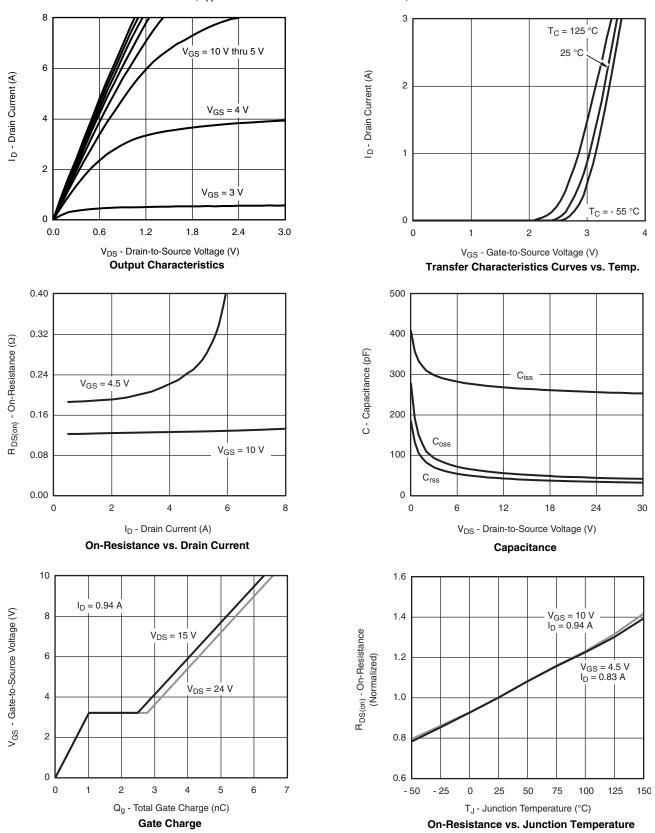
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







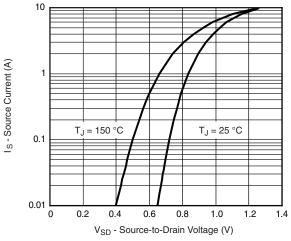
## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



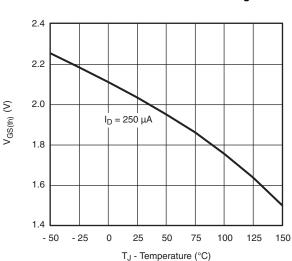
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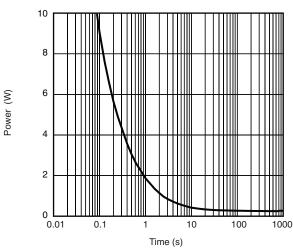




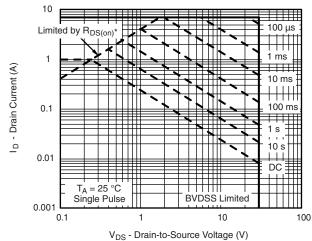


**Threshold Voltage** 

R<sub>DS(on)</sub> vs. V<sub>GS</sub> vs. Temperature



Single Pulse Power



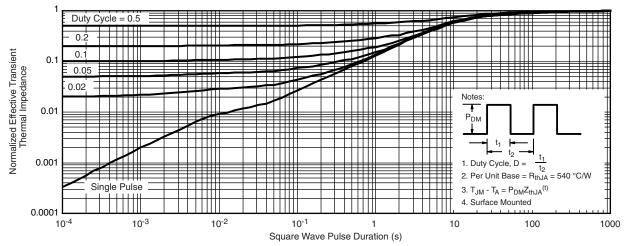
\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area, Junction-to-Ambient





# **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

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